

Acronyms Commonly Used at SBE DG GN-CA T 001

Business Management System

Revision: 1

Last revised by: Antonio Berrio

On: 2018/03/15

Approved by: Karanpaul Dhindsa

1. Purpose

The purpose of the present document is to provide a list of acronyms commonly used at SBE.

2. Scope

This document applies to all managers, supervisors, team leaders and technicians working at SBE Canada.

3. Revision History

Revision	Reason	Date
1	Document creation	15/03/2018
2		
3		
4		
5		

4. Definitions

ARTEMIS - Advanced Real Time Electronic Maintenance Information System

5. Documents

N/A

6. Acronyms Commonly Used at SBE

An Acronym is an abbreviation formed from the initial letters of other words and pronounced as a word (e.g., DOA).

TAT- **Turn Around Time**. The amount of time to repair a device, this is measured from the time/date the device is logged in to the time of completion. This is based on a first in first out (FIFO) methodology.

WIP- Work In Progress. Refers to the WIP portal. This is a unified login system that allows you to access certain SBE services which help to drive productivity. The WIP portal allows the user to check how many devices are currently in SBE systems as well as filter them according to manufacturer, status and other parameters.

SLA- **Service Level Agreement**. Official commitment that prevails between SBE and a client. Particular aspects of the service – quality, availability, responsibilities – are agreed between SBE and the client.



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RMA- Return Merchandise Authorization. Is a part of the process of returning a product to receive a refund, replacement, or repair during the product's warranty period. Sometimes known as RA (Return Authorization) or RGA (Return of Goods Authorization)

CID- Customer Induced Damage. Damage found on a device that is determined to be caused by the customer or end user.

NFF- **No Fault Found**. When a device has been sent for repair for an issue but when tested the device works correctly and no fault is found

IW- In Warranty. A written guarantee, issued to the purchaser of a device by its manufacturer, promising to repair or replace (under certain circumstances) it if necessary within a specified period of time.

OOW- **Out of Warranty**. When the specified warranty time period has expired or if the device is found to be CID (Customer Induced Damage)it is known as out of warranty

IEW- In Exceptional Warranty. Under certain circumstances a Manufacturer will cover certain criteria that is not usually covered by a standard warranty. This is known as In Exceptional Warranty, details of this type of warranty can be found in service bulletins

EPW- Extended Partial Warranty. A prolonged warranty offered to customers in addition to the standard warranty on a device. These can vary from manufacturer to manufacturer and can be found in service bulletins

NPI- **New Product Introduction**. When a new device is released or launched, SBE receives new product information with regards to warranty, repairs and service bulletins. This information can currently be found in the Ahone technical folder and in the future, will be on DMS (Document Management System)

BTT- Back To Technician. If a repair has been attempted but does not pass quality control checks it goes back to the technician

DOA- **Dead On Arrival**. When a device is purchased new and a fault is detected immediately then these handsets are referred to as DOA

OEM- Original Equipment Manufacturer. Usually refers to the manufacturer of a device for example Apple or Samsung.

DOM- **Date Of Manufacture**. The date at which the device was produced or made. This is different to the date at which the device was *bought*.

POP- **Proof of Purchase**. Confirmation in the form of a receipt or other document that a customer has paid for a particular item, sometimes found on a invoice.



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BER- Beyond Economical Repair. When a device is received and its estimated repair cost significantly exceeds a certain percentage of its replacement value it is deemed BER

LDI- Liquid Damage Indicator. Usually a small indicator that turns from white into another color, typically red, after contact with water

MB- Main Board. Sometimes known as motherboard, logic board or main printed circuit board (PCB). It holds together many of the crucial components of an electronic device, including the central processing unit (CPU), memory and connectors for input and output devices.

QC- **Quality Control**. Quality control (QC) is a procedure or set of procedures intended to ensure that the performed service provided by SBE adheres to a defined set of quality criteria or meets the requirements of the client or customer.

ESD- Electrostatic Discharge. The sudden flow of electricity between two electrically charged objects caused by contact, ESD can damage electronic devices and components so we must take precautions such as wearing ESD gloves, ESD smocks and footstraps where appropriate.

MRC- Material Return Collection. This refers to parts used during the repair or refurbishment of a device. When parts are used they should be marked for working quality and cosmetic grade.

RTV- Return to Vendor. Refers to the process where goods are returned to the original vendor

RO- **Repair Only**. Refers to the process whereby a technician repairs the faults on a device only. The cosmetic condition of the device is not changed, this is usually associated with Same Unit Repairs (SUR)

RR-Repair and Refurbish. The process whereby the technician repairs all faults on a device and cosmetically refurbishes the device so it looks as new, this is usually associated with Bulk Repairs.

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